



Material Content Data Sheet



Halogen-Free

Sales Product Name	ISC031N10NM6	Issued	08. February 2022
MA#	MA005428580		
Package	PG-TDSON-8-26	Weight*	116.33 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.010	1.73	1.73	17278	17278
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		126	
	non noble metal	iron	7439-89-6	0.049	0.04		420	
	non noble metal	copper	7440-50-8	48.769	41.93	41.98	419217	419763
wire	noble metal	gold	7440-57-5	0.045	0.04	0.04	386	386
encapsulation	organic material	carbon black	1333-86-4	0.081	0.07		699	
	plastics	epoxy resin	-	6.423	5.52		55209	
	inorganic material	silicondioxide	60676-86-0	34.146	29.35	34.94	293518	349426
leadfinish	non noble metal	tin	7440-31-5	1.392	1.20	1.20	11962	11962
plating	noble metal	silver	7440-22-4	0.194	0.17	0.17	1666	1666
solder	non noble metal	tin	7440-31-5	0.049	0.04		421	
	noble metal	silver	7440-22-4	0.061	0.05		526	
	non noble metal	lead	7439-92-1	2.336	2.01	2.10	20081	21028
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			44	
	non noble metal	iron	7439-89-6	0.017	0.01		147	
	noble metal	silver	7440-22-4	0.635	0.55		5463	
	non noble metal	copper	7440-50-8	17.131	14.73	15.29	147261	152915
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			8	
	non noble metal	iron	7439-89-6	0.003			26	
	non noble metal	copper	7440-50-8	2.971	2.55	2.55	25542	25576
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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